CONFERENCES OF THE CPMT SOCIETY

Calendar

53rd IEEE Holm Conference on Electrical Contacts, and Intensive Course

September 16-19, 2007; Sheraton Station Square Hotel, Pittsburgh, PA USA
Contact: Elsie Cabrera, IEEE, e.cabrera@ieee.org
www.ewh.ieee.org/soc/cpmt/tc1/h2007/h2007top.html

3D System Integration Workshop – The Future Technology!

October 1-2, 2007; Fraunhofer Gesellschaft, München Germany
Contact: Simone Brand, Fraunhofer IZM, simone.brand@izm-m.fraunhofer.de
www.pb.izm.fhg.de/izm/050_Events/90_single/81_3d.html

Int'l Microsystems, Packaging, Assembly and Circuits Technology (IMPACT) Conference

October 1-3, 2007; Taipei International Convention Center, Taiwan
20% discount through August 31st
Contact: Wendy Huang, Conference Secretariat, impact@itri.org.tw
impact.itri.org.tw

34th Int'l Electronics Manufacturing Technology Symposium (IEMT 2007)

October 3-5, 2007
Holiday Inn, San Jose (Silicon Valley), CA USA
Discount through Sept. 17th
Contact: Paul Wesling, p.wesling@ieee.org
www.cpmt.org/iemt/

Advanced Packaging Materials Symposium (APM 2007)

October 3-5, 2007
Holiday Inn, San Jose (Silicon Valley), CA USA
Discount through Sept. 17th
Contact: Paul Wesling, p.wesling@ieee.org
www.cpmt.org/apm/

16th Annual International Symposium on Semiconductor Manufacturing (ISSM'07)

October 15-17, 2007, Marriott Hotel, Santa Clara, CA USA
Contact: Maria Hess, AMD, maria.hess@amd.com
www.issm.com

For quick-links, go to our Society Conferences Page:

www.cpmt.org/conf

2007 IEEE Electrical Performance of Electronic Packaging (EPEP)

October 29-31, 2007
Renaissance Atlanta Hotel Downtown, Atlanta, GA USA
Contact: Kelly Sutton, University of Arizona, epd@engr.arizona.edu
www.epep.org

2007 IEEE/CPMT Workshop on Accelerated Stress Test and Reliability (AST)

October 31 - November 2, 2007; Greenbelt Marriot in Greenbelt, Maryland USA
Contact: Kirk Gray, Dell Computer, Kirk_Gray@Dell.com
www.ewh.ieee.org/soc/cpmt/tc7/ast2007

2007 International Symposium on Electronic Materials and Packaging (EMAP2007)

November 19-22, 2007; KAIST (Korea Advanced Institute of Science & Technology), Daejon, Korea
Abstracts Due July 31, 2007
Contact: For more information, email emap@kaist.ac.kr
emap.kaist.ac.kr

9th Electronics Packaging Technology Conference (EPTC 2007)

December 10-12, 2007; Singapore
Early registration discount thru October 22nd
Contact: Joseph LIM, eptc2007@elite.sg
www.eptc-ieee.net

2007 IEEE Electrical Design of Advanced Packaging and Systems (EDAPS)

December 15-17, 2007; Taipei, Taiwan
Contact: Hui-Yun Hu, EDAPS Secretariat, edaps2007@tl.ntu.edu.tw
edaps2007.ntu.edu.tw

2008 Systems Packaging Japan Worshop (SPJW)

January 28-30, 2008 Hotel de Yama, Hakone, Japan
Abstracts Due Nov 20, 2007
Contact: Kishio Yokouchi, Fujitsu Interconnect Technologies Ltd., yokouchi.kishio@fict.fujitsu.com
www.ewh.ieee.org/soc/cpmt/tc14/Japan08/SWJ08call.html